



METC 143 LAB NOTEBOOK

SPRING 2014

Tanner



INSTRON 5960 DUAL COLUMN TABLETOP UNIVERSAL TESTING SYSTEM

By: "Wild" Billy and Tanner

What it is.

- We know it best as one of our tensile testers
- Universal, static testing systems that perform tensile and compression testing
- Can also perform shear, flexure, peel, tear, cyclic, and bend tests.



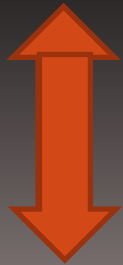


Features

- Load measurement accuracy: $\pm 0.5\%$
- Up to 2.5 kHz data acquisition rate
- Speed range of 0.001 - 3000 mm/min
- 50 kN (11,250 lbs) capacity
- 1212 mm (47.7 in) vertical test space

How it works

- Pressure is applied from various directions, to test different properties of the metal.
 - Compression
 - Tension
 - As well as a variety of other tests



Instron in Action!!!!

- <http://www.youtube.com/watch?v=ivTHHyHTjNU>



Source

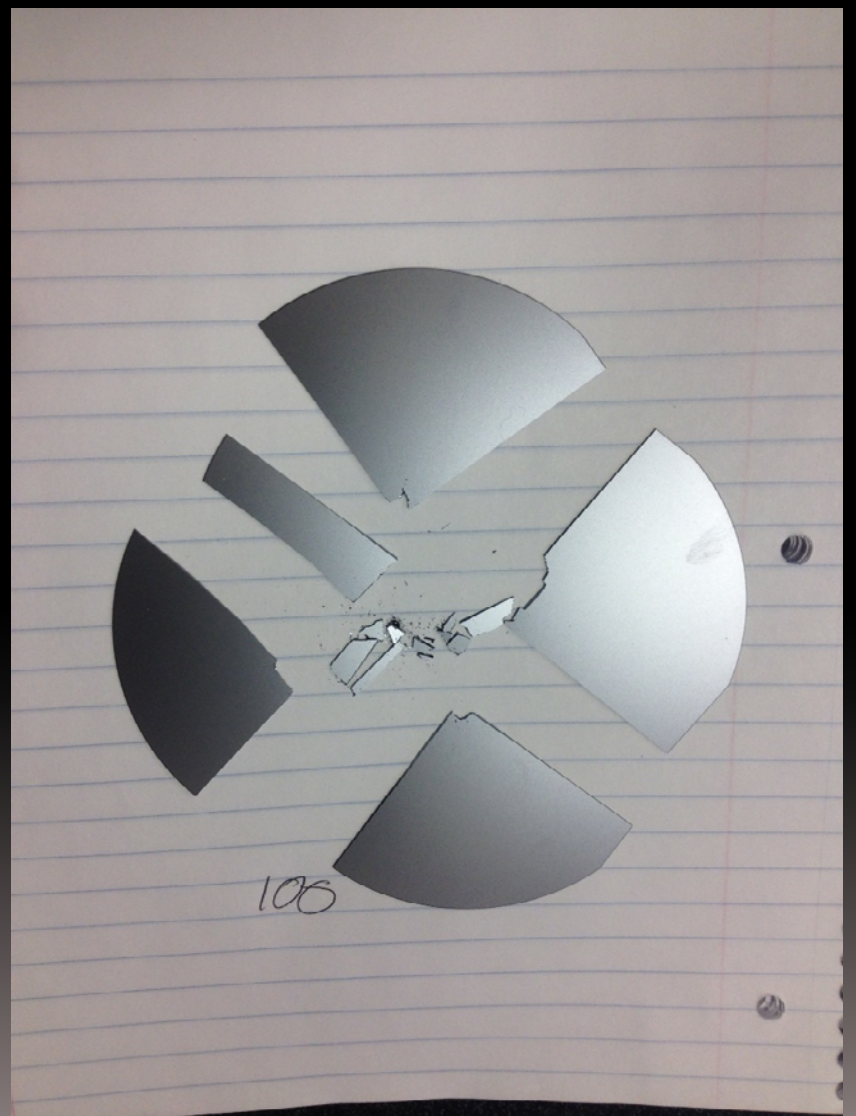
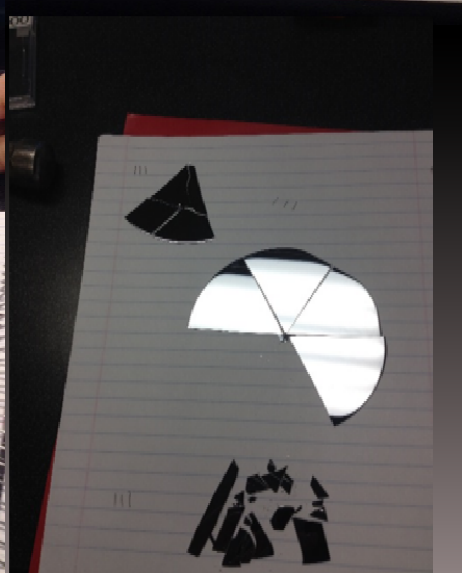
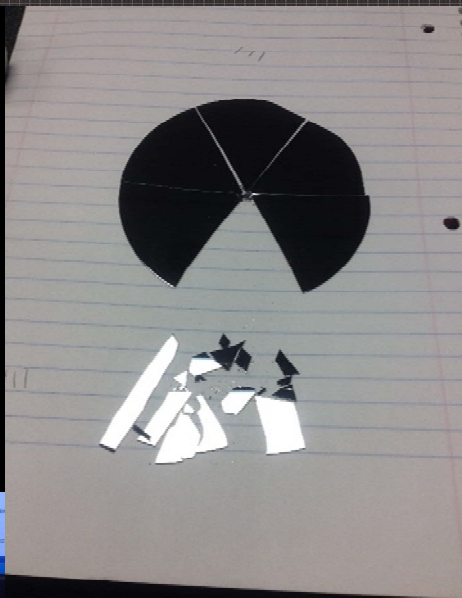
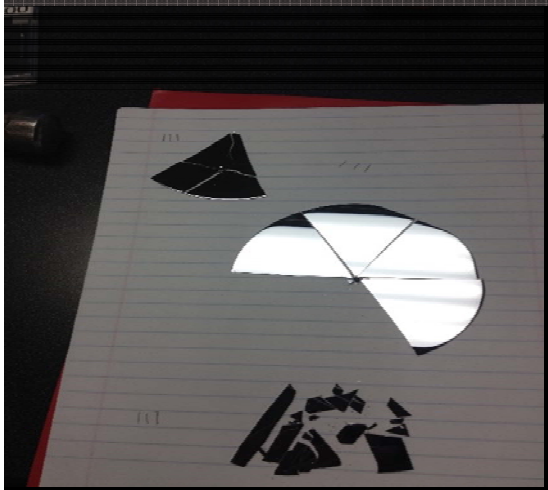
<http://www.instron.us/wa/product/5960-Dual-Column-Testing-Systems.aspx>



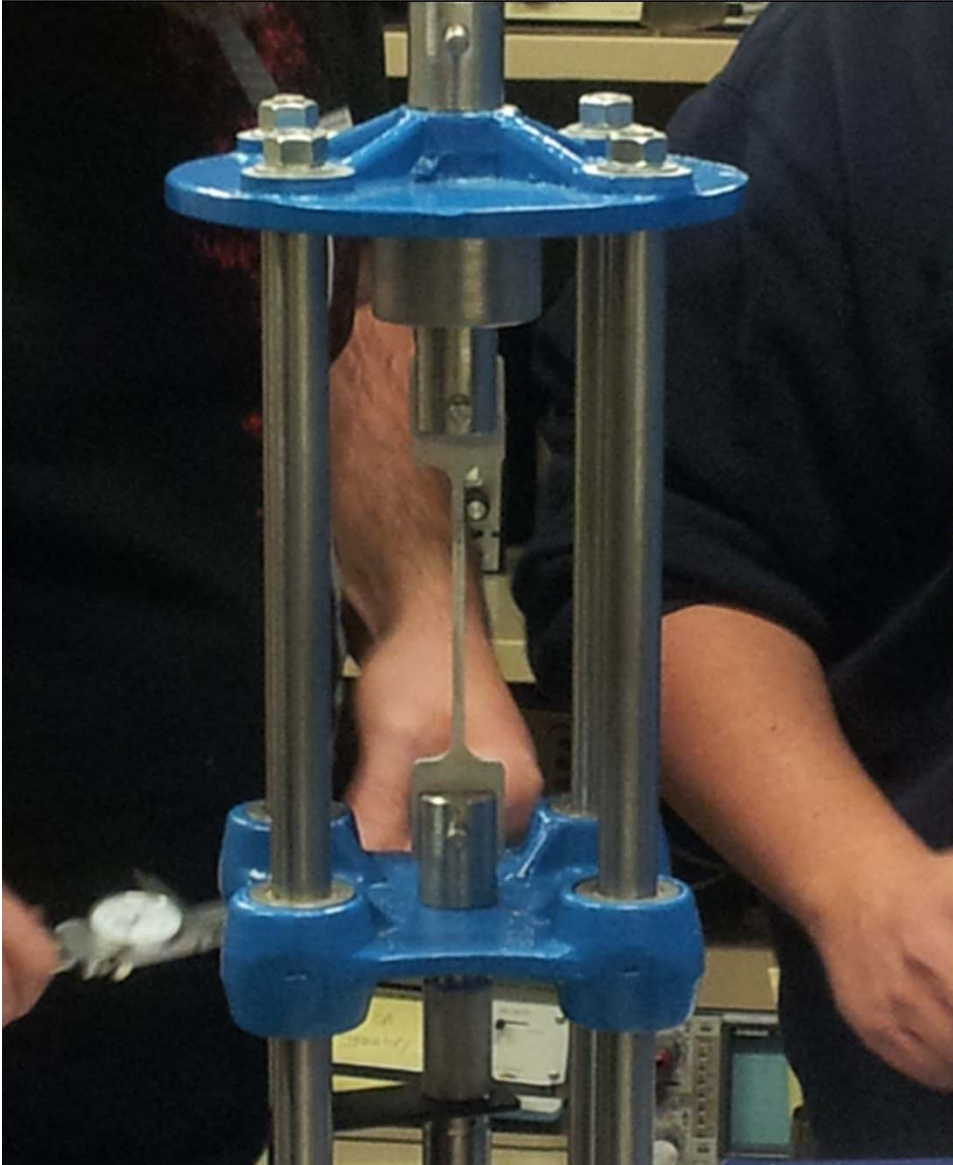
Lab 2/ Crystallography Lab

- Post-Activity Questions
- 1. In this activity, you broke two silicon wafers. One wafer had a (100) crystal surface plane orientation and the other a (111) surface plane orientation. In the making of the original silicon ingot, what determined the crystal orientation of the silicon wafer? The number of surface atoms are
- 2. At what approximate angle did the (111) wafer break? It broke into 6 separate 60 degree pieces
- 3. At what approximate angle did the (100) wafer break? It broke into 4 separate 90 degrees pieces
- 4. Did each wafer continue to break at the same angle when you broke the smaller pieces?
- Why or why not? Silicon wafer (100) broke an individual piece for second time the results were not exactly 4 90 degree pieces like before but for the most part rectangles or perfect squares. Silicon wafer (111) when a piece was broken for a second time, broke into 6 almost exact representational pieces of the original broken pieces as the first break was.
- 5. Which orientation (100) or (111) has more silicon atoms exposed to the wafer's surface? 111
- 6. Why is crystal orientation important in the fabrication of microsystems? To be able to know and produce a piece of material with the necessary requirements that particular piece of material needs to at hear to.
- 7. Identify the crystal orientation of each of the following pieces of silicon.

Lab 2 Cont.....

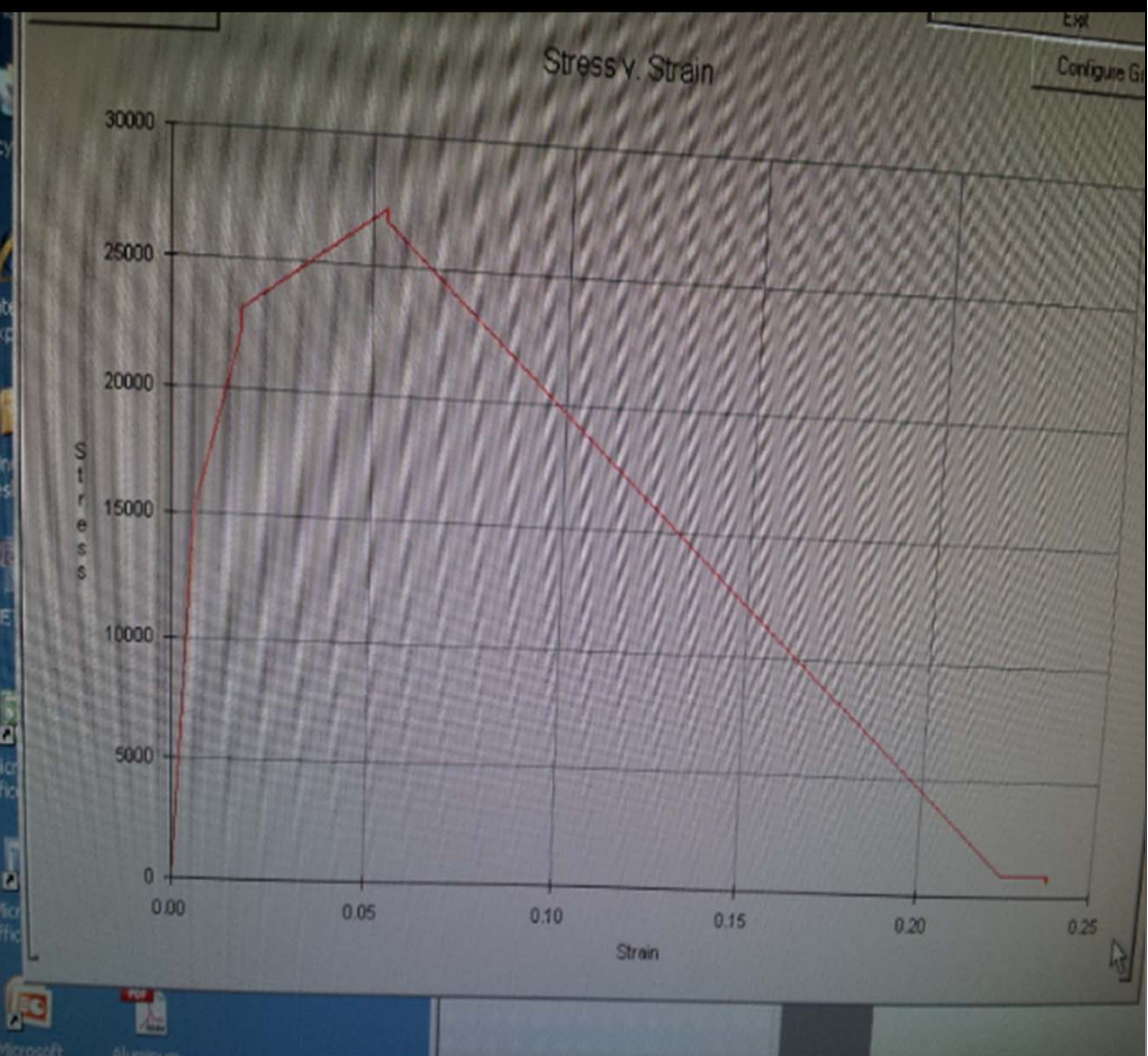


Lab 3 T9014 Aluminum

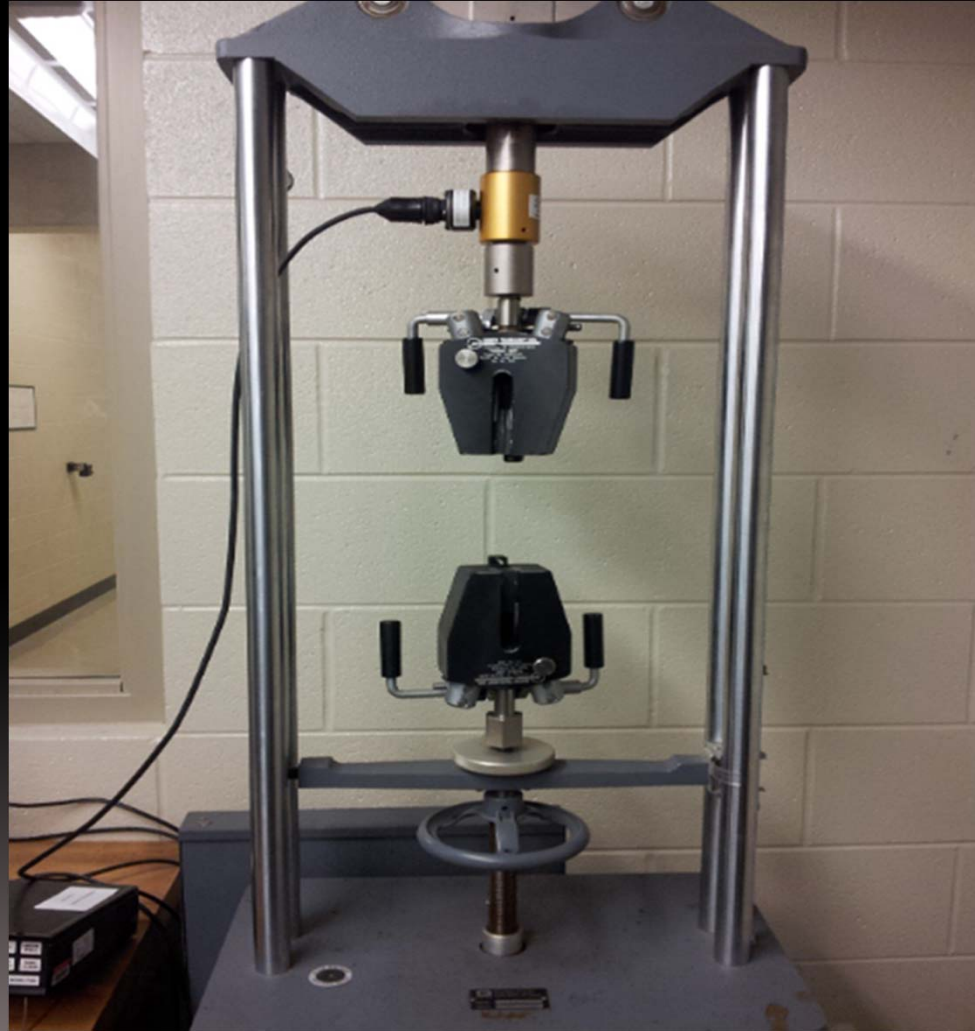




Lab 3 Cont.....



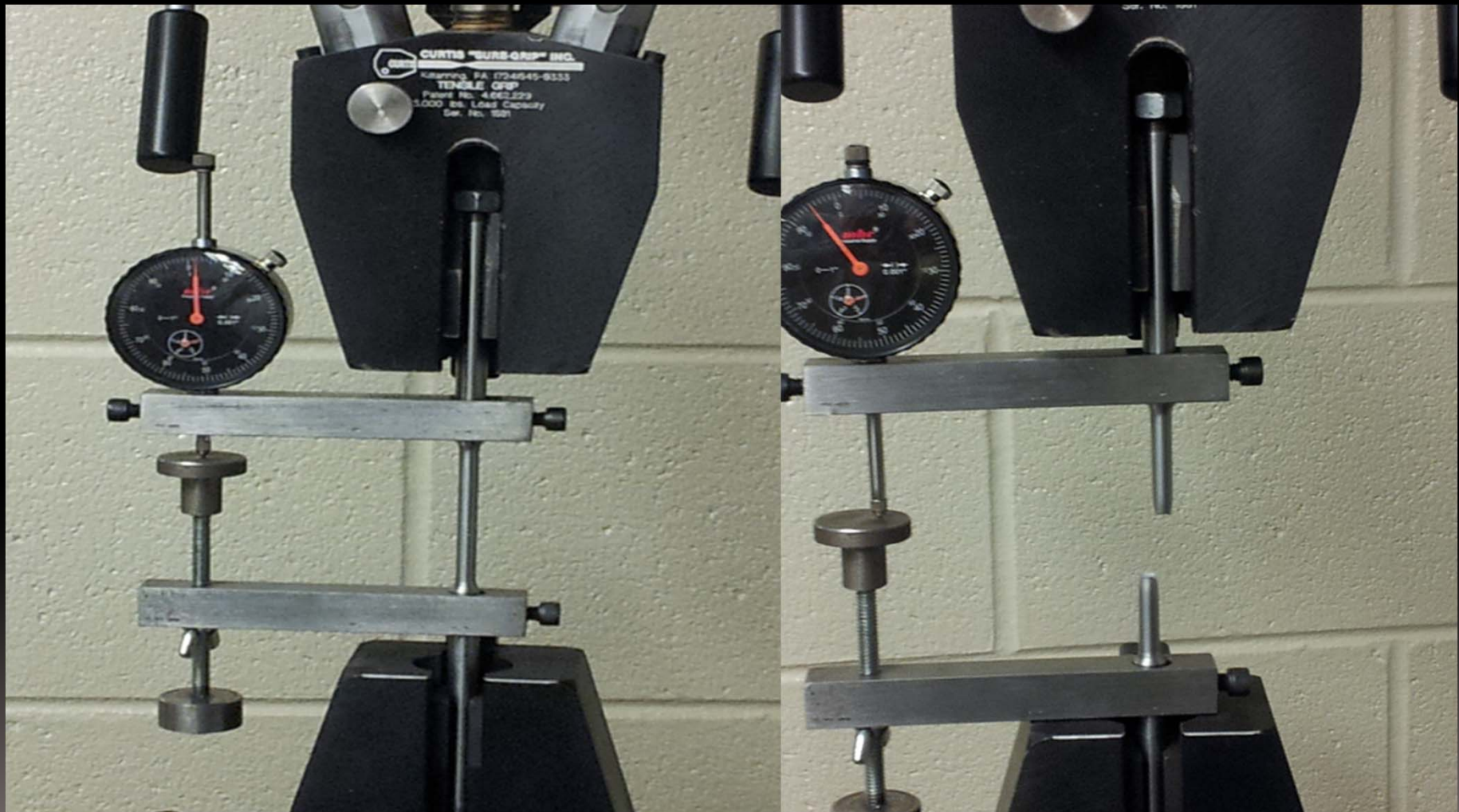
Lab 4: TC1548 Steel Tensile Tester



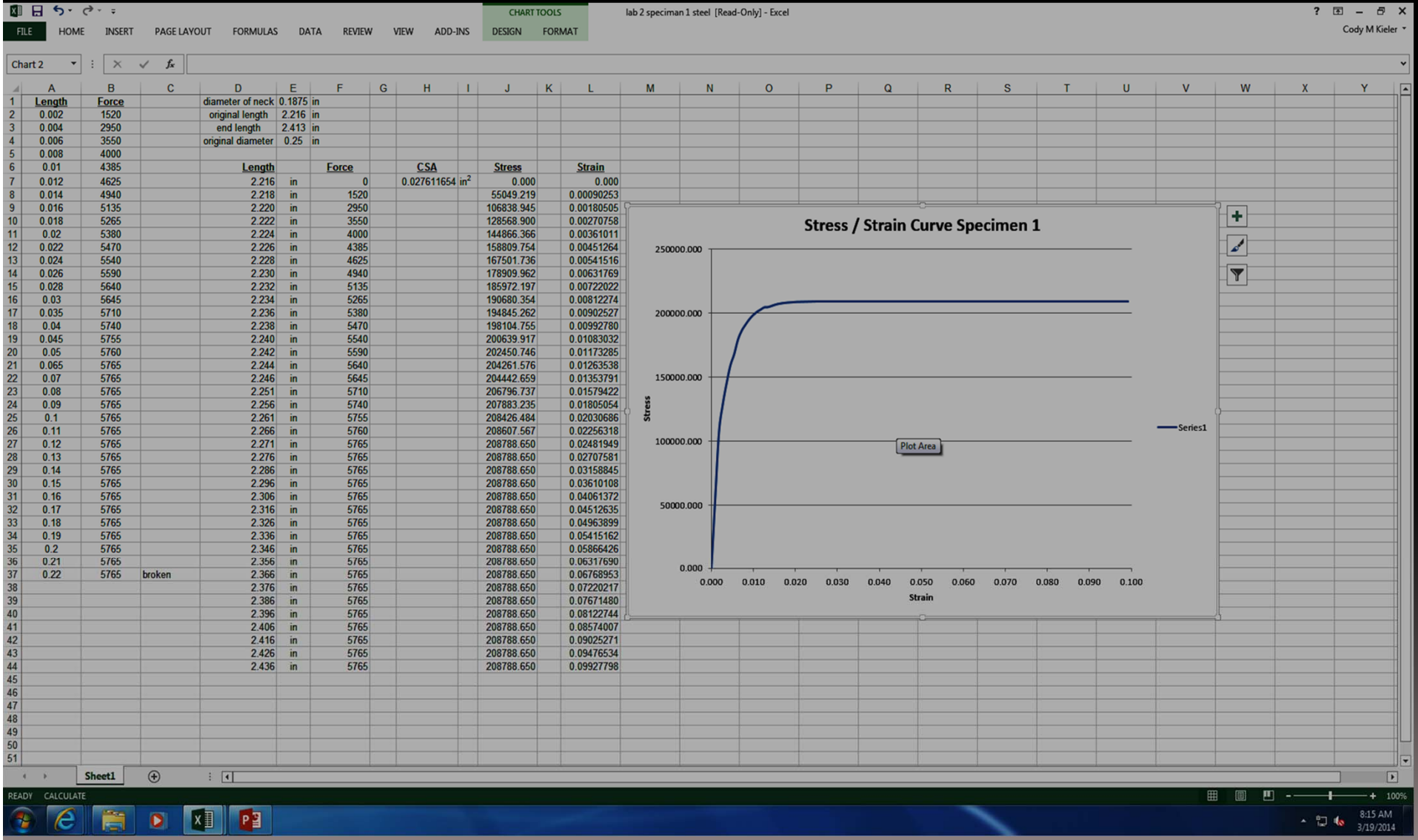
Lab 4: Cont....



Lab 4: Cont.....



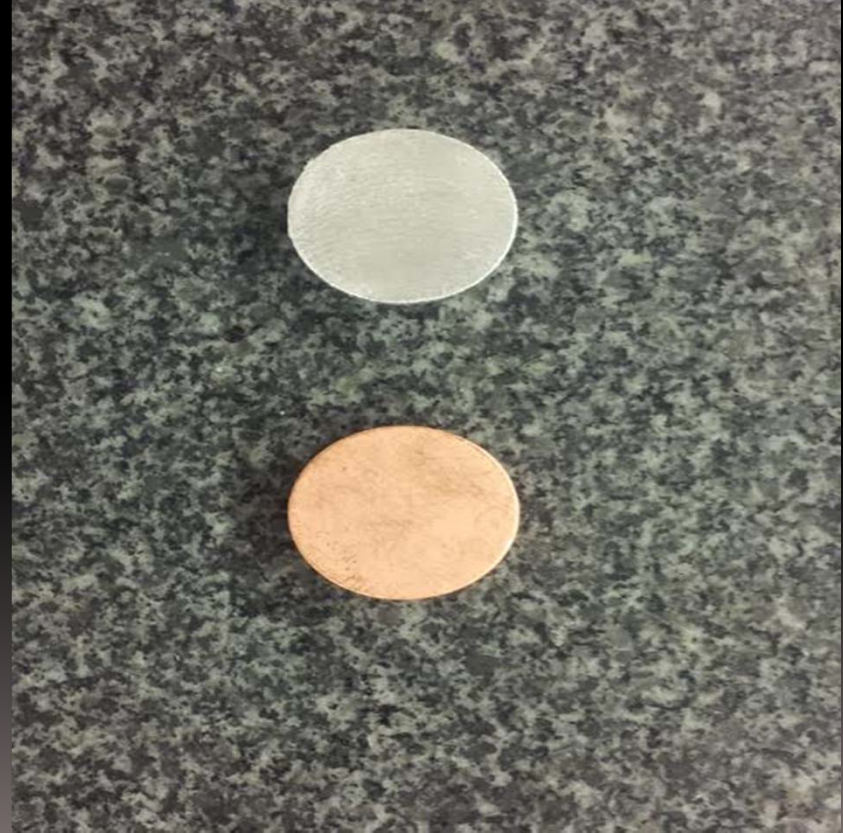
Lab 4: Cont...



Lab 5: Brinell & Rockwell Hardness Testing on Cu/Al



Lab 5: Cont....



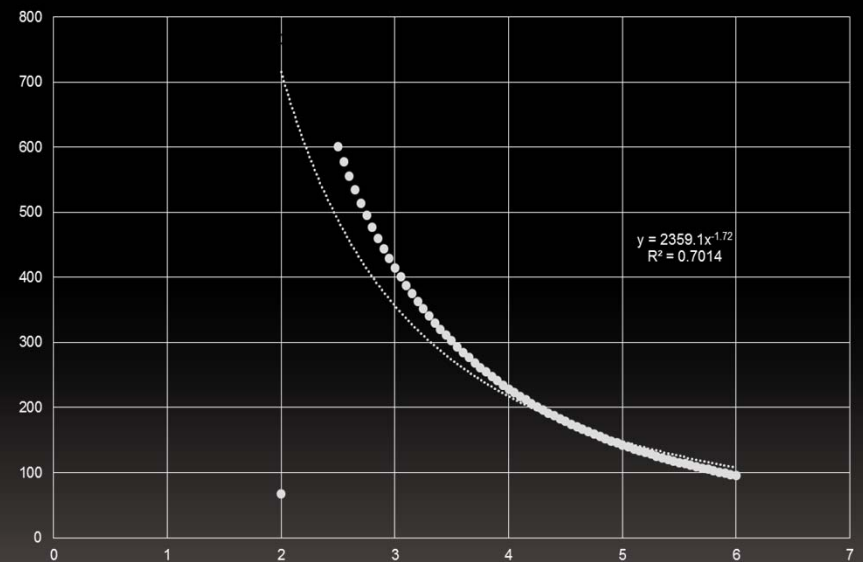
Lab 5: Cont... Cu sample



Lab 5: Cont...

Froce	3000	kg
PI()	3.141593	
Diameter	10	mm
d	6.98	mm
HB=	67.27172	

Copper Trend Line



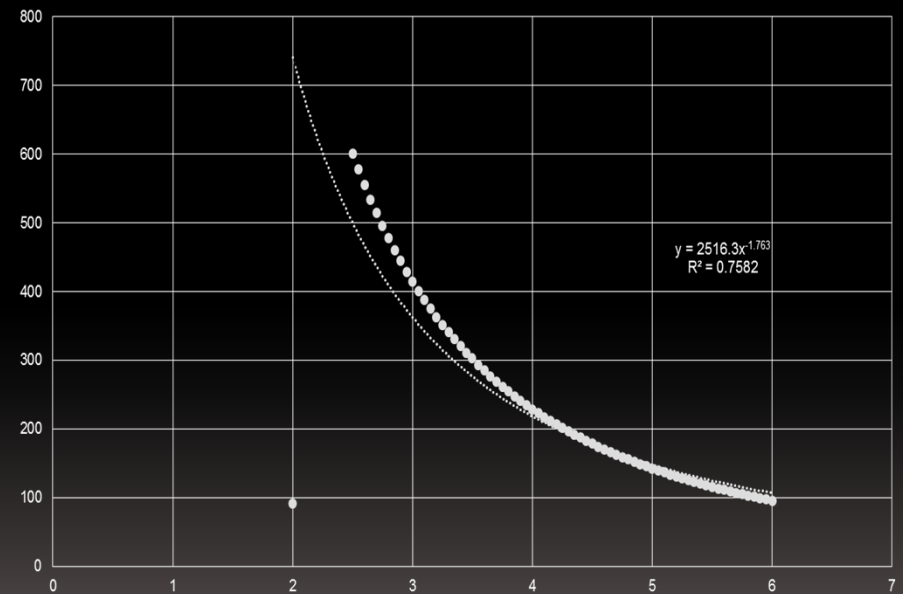
Lab 5: Cont.... Al sample



Lab 5: Cont...

Froce	3000 kg
PI()	3.141593
Diameter	10 mm
d	6.13 mm
HB=	90.9816

AI Trend line Curve



Lab 6: Beginning of Pasco Strength Tester

Making our samples



Lab 7: Rockwell Hardness Test of Al, Steel, & Brass

